

TIF™ 050AB-11S Series is a highly thermal conductive, liquid gap filling material. It is provided with two-component and different temperature curing systems. The product is supplied as highly thermal conductive, soft and elastomer for coupling on electrical devices modules. Heat can transmit to the metal housing or dissipation plate from the separate elements or even the entire PCB, which in effect enhances the efficiency and life-time of the heat-generating electronic components. It is liquid approach offers variety of thickness, replacing individual die-cut and specific pad thickness. Different from grease, the cured product is dry and can be touched. It is intended for use in thermal applications.

Features

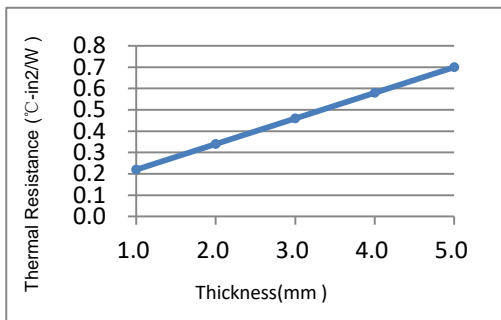
- › Good thermal conductivity: **5.0 W/mK**
- › Two-part formulation for easy storage
- › Excellent low and high temperature mechanical and chemical stability
- › Ultra-conforming low-stress interface application
- › Ambient or accelerated cure schedules
- › Optimized shear thinning characteristics for ease of dispensing

Application

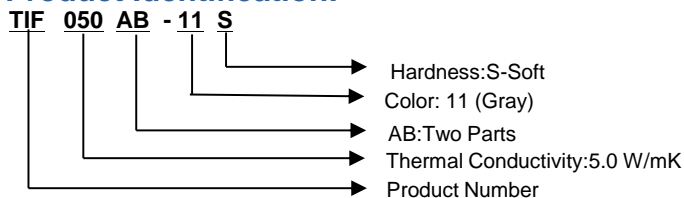
- › Computer and peripherals
- › Telecommunications
- › Automotive electronics
- › Thermally conductive vibration dampening
- › Heat sink and any heat generating semiconductor

Typical Properties of TIF™ 050AB-11S Series		
Typical Uncured Material		
PROPERTY	NUMERICAL	TEST METHOD
Color/Part A	White	Visual
Color/Part B	Gray	Visual
Viscosity as Mixed (cps)	1500,000cPs	GB/T 10247
Density	3.0 g/cc	ASTM D792
Mix Ratio	1:1	*****
Shelf Life@25°C	6 months	*****
Cure Schedule		
Pot Life @ 25°C	30 min	*****
Cure @ 25°C	60 min	*****
Cure @ 100°C	30 min	*****
Cure Properties		
Color	Gray	Visual
Hardness	45 Shore 00	ASTM D2240
Continuous Use Temp	-45 ~ 200°C	*****
Voltage Strength	200 V/mil	ASTM D149
Dielectric Constant	4.1 MHz	ASTM D150
Volume Resistivity	10 ¹² Ohm-meter	ASTM D257
Flame Rating	94 V0	E331100
Thermal Conductivity	5.0 W/mk	ISO22007-2
Specific heat capacity	2.3 MJ/m ³ K	ISO22007-2

Thermal impedance



Product Identification:



Thermal Conductive Interface Materials Application Technology Download



<http://www.ziitek.com>

Product Specification

50 cc/pc, 48 pc/box; 400 cc/pc, 9 pc/box

We offer the custom packaged in syringes for automated dispensing applications. Please contact us for confirming.

Thermally Conductive Materials | Thermally Conductive Plastics | Heat Generating Materials | Shielding Materials | Foaming Silica Gel | Die-Cutting Products

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